

## 2A, 23V, 380KHz Step-Down Converter



## **General Description**

The FP6181 is a buck regulator with a built in internal power MOSFET. It achieves 2A continuous output current over a wide input supply range with excellent load and line regulation. Current mode operation provides fast transient response and eases loop stabilization. The device includes cycle-by-cycle current limiting and thermal shutdown protection. Adjustable soft-start reduced the stress on the input source at power-on. The regulator only consumes 23µA supply current in shutdown mode. The FP6181 requires a minimum number of readily available external components to complete a 2A buck regulator solution.

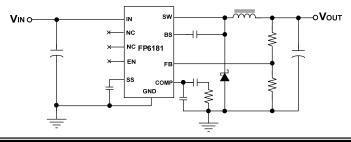
### **Features**

- 2A Output Current
- > Adjustable Soft-Start
- > 0.18Ω Internal Power MOSFET Switch
- > Stable with Low ESR Output Ceramic Capacitors
- ➤ Up to 95% Efficiency
- > 23µA Shutdown Mode Current
- > Fixed 380KHz frequency
- > Thermal Shutdown
- Cycle-by-Cycle Over Current Protection
- ➤ Wide 4.75 to 23V operating Input Range
- Output Adjustable From 0.92 to 16V
- Available MSOP10 With Exposed PAD
- Under Voltage Lockout.

### **Applications**

- Distributed Power Systems
- Battery Charger
- Pre-Regulator for Linear Regulators
- DSL Modems

## **Typical Application Circuit**

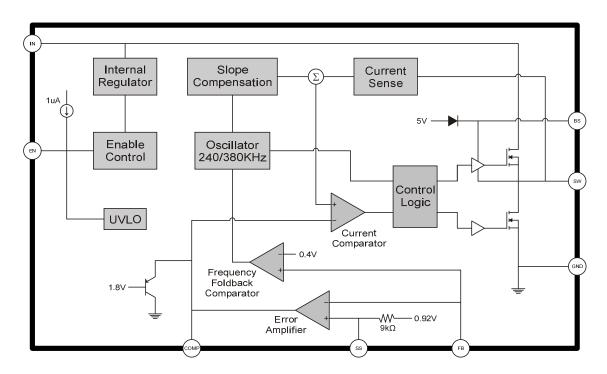


This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.

Website: http://www.feeling-tech.com.tw

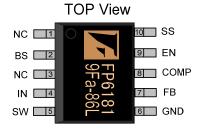


# **Function Block Diagram**



# **Pin Descriptions**

### MSOP-10L (EP)







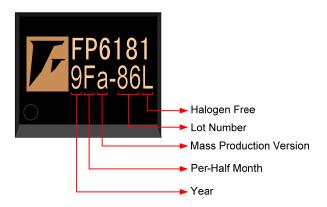
Name	No.	1/0	Description
NC	1		No connect
BS	2	0	Bootstrap
NC	3		No connect
IN	4	Р	Supply Voltage
SW	5	0	Switch
GND	6	Р	Ground
FB	7	I	Feedback
COMP	8	0	Compensation
EN	9	I	Enable / UVLO
SS	10	0	Programmable Soft Start

This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.



### **IC Date Code Identification**

## MSOP-10L (EP)



Halogen Free: Halogen free product indicator

Lot Number: Wafer lot number's last two digits

For Example: 132386TB → 86

Mass Production Version: Mass production mask version

Per-Half Month: Production period indicated in half month time unit

For Example: January  $\rightarrow$  A (Front Half Month), B (Last Half Month)

February → C (Front Half Month), D (Last Half Month)

Year: Production year's last digit

This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.



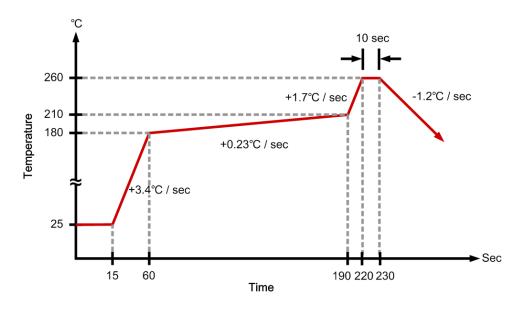
**Ordering Information** 

Part Number	Operating Temperature	Package	MOQ	Description
FP6181g-G1	-40°C ~ +85°C	MSOP-10L (Exposed PAD)	80EA	Tube
FP6181gR-G1	-40°C ~ +85°C	MSOP-10L (Exposed PAD)	2500EA	Tape & Reel

**Absolute Maximum Ratings** 

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply Voltage (V <sub>IN</sub> )			-0.3		24	V
Switch Voltage (V <sub>SW</sub> )			-1		V <sub>IN</sub> +0.3	V
Boost Voltage (V <sub>BS</sub> )			V <sub>SW</sub> -0.3		V <sub>SW</sub> +6	V
All Other Pins			-0.3V		6	V
Thermal Desistance	$\theta_{JA}$	MCOD 40L (ED)			+105	°C / W
Thermal Resistance	$\theta_{JC}$	MSOP-10L (EP)			+19	°C / W
Junction Temperature					+150	°C
Storage Temperature			-65		+150	°C
Operating temperature			-40		+85	°C
Lead Temperature (soldering, 10 sec)					+260	°C
Allowable Power Dissipation $(T_A \leq +25^\circ)$					800	mW

# **IR Re-flow Soldering Curve**



This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.



# **Recommended Operating Conditions**

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply Voltage	$V_{IN}$		4.75		23	٧
Operating Temperature			-40		+85	°C

# **DC Electrical Characteristics** (T<sub>A</sub>= 25°C, V<sub>IN</sub>=3.6V, unless otherwise noted)

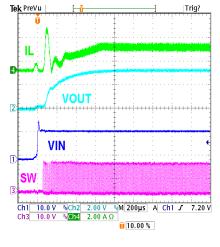
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Standby Current	I <sub>ST</sub>	V <sub>EN</sub> ≧3V,V <sub>FB</sub> >1V		0.6		mA
Shutdown Supply Current	I <sub>ST</sub>	V <sub>EN</sub> =0		23	36	μA
Feedback Voltage	$V_{FB}$	V <sub>IN</sub> =12V,V <sub>COMP</sub> <2V	0.892	0.920	0.948	V
Current Sense Tran conductance Output Current to Comp Pin Voltage	T <sub>CS</sub>			2.1		A/V
Error Amplifier Voltage Gain	$G_{EA}$			400		V / V
Error Amplifier Tran conductance	T <sub>EA</sub>	△IC=±10μA		830		μA / V
High Side Switch ON Resistance	R <sub>ON-HS</sub>			0.18		Ω
Low Side Switch ON Resistance	R <sub>ON-LS</sub>			10		Ω
High Side Switch Leakage Current	I <sub>IL</sub>	V <sub>EN</sub> =0,V <sub>SW</sub> =0V		0.1	10	μΑ
Current Limit	I <sub>CL</sub>		2.8	3.4		Α
Oscillation Frequency	f <sub>OSC</sub>			380		KHz
Short Circuit Oscillation Frequency	f <sub>SC</sub>	V <sub>FB</sub> =0V		240		KHz
Maximum Duty Cycle	$D_{MAX}$	V <sub>FB</sub> =0.8V		90		%
Minimum On Time	t <sub>ON</sub>	V <sub>FB</sub> =1.5V		100		ns
Under Voltage Lockout Threshold	$V_{\text{UVLO}}$	V <sub>EN</sub> Rising	2.37	2.50	2.62	V
Under Voltage Lockout Threshold Hysteresis	V <sub>HYS</sub>			210		mV
EN Threshold Voltage	$V_{EN}$	ICC>100μA	0.7	1.0	1.3	V
Enable Pull Up Current	I <sub>EN</sub>	V <sub>EN</sub> =0V		1.0		μA
Soft-Start Pin Equivalent Output Resistance	R <sub>SS</sub>			9		kΩ
Thermal Shutdown	$T_TS$			150		°C
Thermal Shutdown Reset Hysteresis	T <sub>HYS</sub>			40		°C

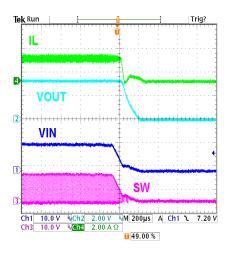
This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.

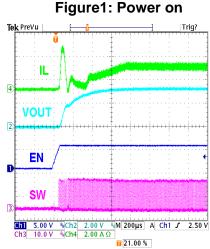


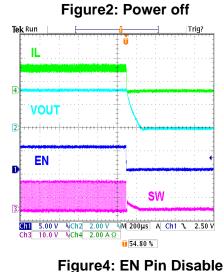
## **Typical Operating Characteristics**

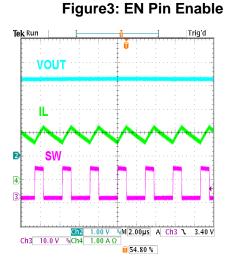
(T<sub>A</sub>= 25°C, V<sub>IN</sub>=12V, unless otherwise noted)











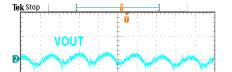


Figure6: Load 2A Ripple

Figure5: Load 2A

This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.

Website: http://www.feeling-tech.com.tw



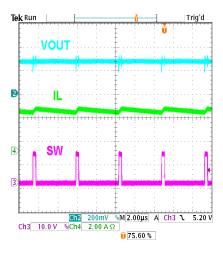


Figure7: SCP

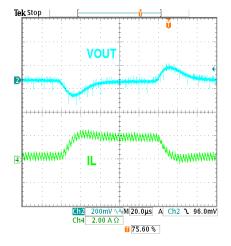


Figure9: Load Step

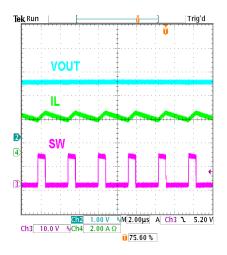


Figure8: OCP

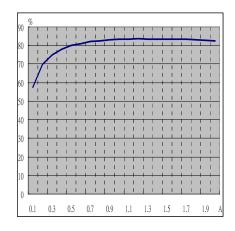


Figure10: Efficiency V<sub>IN</sub>=12V V<sub>OUT</sub>=3.3V

This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.



## **Function Description**

The FP6181 is a current-mode buck regulator. It regulates input voltages from 4.75V to 23V down to an output voltage as low as 0.92V, and is able to supply up to 2A of load current. The FP6181 uses current-mode control to regulate the output voltage. The output voltage is measured at FB through a resistive voltage divider and amplified through the internal error amplifier. The output current of the Tran conductance error amplifier is presented at COMP where a network compensates the regulation control system. The voltage at COMP is compared to the switch current measured internally to control the output voltage.

The converter uses an internal n-channel MOSFET switch to step-down the input voltage to the regulated output voltage. Since the MOSFET requires a gate voltage greater than the input voltage, a boost capacitor connected between SW and BS drives the gate. The capacitor is internally charged while the switch is off. An internal  $10\Omega$  switch from SW to GND is used to insure that SW is pulled to GND when the switch is off to fully charge the BS capacitor.

### **Output Voltage (VOUT)**

The output voltage is set using a resistive voltage divider from the output voltage to FB. The voltage divider divides the output voltage down by the ratio:

$$V_{FB} = V_{OUT} \times \frac{R_4}{R_2 + R_4}$$

Thus the output voltage is:

$$V_{OUT} = V_{FB} \times \frac{R_2 + R_4}{R_4}$$

A typical value for R4 can be as high as 100k, but a typical value is 10K.

#### **Shutdown Mode**

Drive enable Pin to ground to shut down the FP6181. Shutdown forces the internal power MOSFET off, turns off all internal circuitry, and reduces the  $V_{\text{IN}}$  supply current to  $20\mu\text{A}$  (type). The enable Pin rising threshold is 1.2V (type). Before any operation begins, the voltage at Enable Pin must exceed 1.2V (type). The Enable Pin input has 100mV hysteresis.

### **Boost High-Side Gate DriVe (BST)**

Since the MOSFET requires a gate voltage greater than the input voltage ,connect a flying bootstrap capacitor between SW and BS to provide the gate-drive voltage to the high-side n-channel MOSFET switch. The capacitor is alternately charged from the internally regulator.

On startup, an internal low-side switch connects SW to ground and charges the BST capacitor to internally regulator voltage. Once the BST capacitor is charged, the internal low-side switch is turned

This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.



off and the BST capacitor voltage provides the necessary enhancement voltage to turn on the high-side switch.

#### **Thermal Shutdown Protection**

The FP6181 features integrated thermal shutdown protection. Thermal shutdown protection limits allowable power dissipation (PD) in the device, and protects the device in the event of a fault condition. When the IC junction temperature exceeds +150°C, an internal thermal sensor signals the shutdown logic, turning off the internal power MOSFET and allowing the IC to cool down. The thermal sensor turns the internal power MOSFET back on after the IC junction temperature cools down to + 110°C, resulting in a pulsed output under continuous thermal overload conditions.

### **Application Information**

### **Input Capacitor Selection**

The input current to the step-down converter is discontinuous, therefore a capacitor is required to supply the AC current to the step-down converter while maintaining the DC input voltage. Use low ESR capacitors for the best performance. Ceramic capacitors are preferred, but tantalum or low-ESR electrolytic capacitors may also suffice.

The input capacitor can be electrolytic, tantalum or ceramic. When using electrolytic or tantalum capacitors, a small, high quality ceramic capacitor, i.e.  $0.1\mu F$ , should be placed as close to the IC as possible.

When using ceramic capacitors, make sure that they have enough capacitance to provide sufficient charge to prevent excessive voltage ripple at input. The input voltage ripple caused by capacitance can be estimated by

$$C_{IN} = \frac{I_O}{f \times \Delta V_{IN}} \times D(1 - D)$$

### **Inductor Selection**

The inductor is required to supply constant current to the output load while being driven by the switched input voltage. A larger value inductor will result in less ripple current that will result in lower output ripple voltage. However, the larger value inductor will have a larger physical size, higher series resistance, and / or lower saturation current. A good rule for determining the inductance to use is to allow the peak-to-peak ripple current in the inductor to be approximately 30% of the maximum switch current limit. Also, make sure that the peak inductor current is below the maximum switch current limit. The inductance value can be calculated by

This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.



$$L = \frac{V_O + V_D}{I_O \gamma f} (1 - D)$$

Where r is the ripple current ratio

RMS current in inductor 
$$I_{Lrms} = I_O \sqrt{1 + \frac{\gamma^2}{12}}$$

### **Output Capacitor Selection**

The output capacitor is required to maintain the DC output voltage. Ceramic, tantalum, or low ESR electrolytic capacitors are recommended. Low ESR capacitors are preferred to keep the output voltage ripple low. The output voltage ripple can be estimated by:

$$\Delta V_{OUT} = \frac{V_{OUT} \times \left(V_{IN} - V_{OUT}\right)}{f \times L \times V_{IN}} * \left( \text{ESR} + \frac{1}{8 \times f \times C_{OUT}} \right)$$

In the case of ceramic capacitors, the impedance at the switching frequency is dominated by the capacitance. The output voltage ripple is mainly caused by the capacitance. In the case of tantalum or electrolytic capacitors, the ESR dominates the impedance at the switching frequency.

I .In the case of ceramic capacitors

$$C_{OUT} = \frac{V_{OUT}}{8 \times f^2 \times L \times \Delta V_{OUT}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)$$

II .In the case of tantalum or electrolytic capacitors

$$\text{ESR} = \frac{\Delta V_{\text{OUT}} \times f \times L \times V_{\text{IN}}}{V_{\text{OUT}} \times \left(V_{\text{IN}} - V_{\text{OUT}}\right)}$$

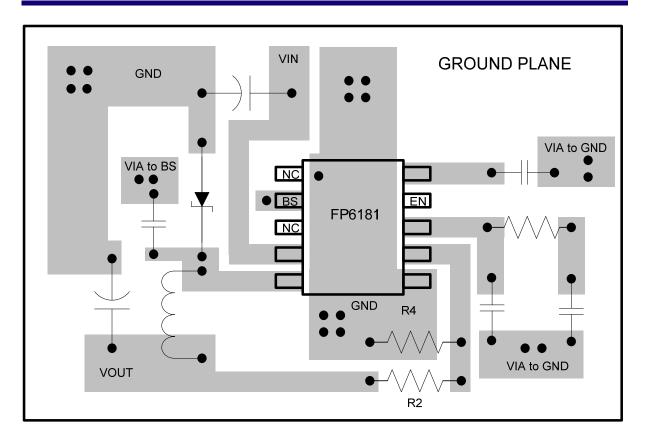
### **PC Board Layout Checklist**

- 1. The power traces, consisting of the GND trace, the SW trace and the VIN trace should be kept short, direct and wide.
- 2. Place C<sub>IN</sub> near IN Pin as closely as possible. To maintain input voltage steady and filter out the pulsing input current.
- The resistive divider R₂and R₄ must be connected to FB pin directly as closely as possible.
- 4. FB is a sensitive node. Please keep it away from switching node, SW. A good approach is to route the feedback trace on another layer and to have a ground plane between the top layer and the layer on which the feedback trace is routed. This reduces EMI radiation on to the DC-DC converter's own voltage feedback trace.

This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.

Website: http://www.feeling-tech.com.tw Rev. 0.61



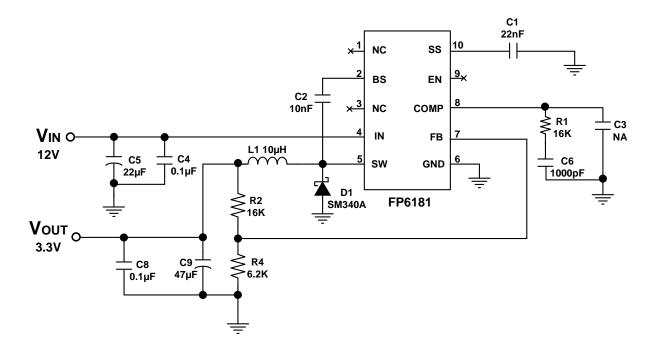


Suggested Layout

This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.



# **Typical Application**

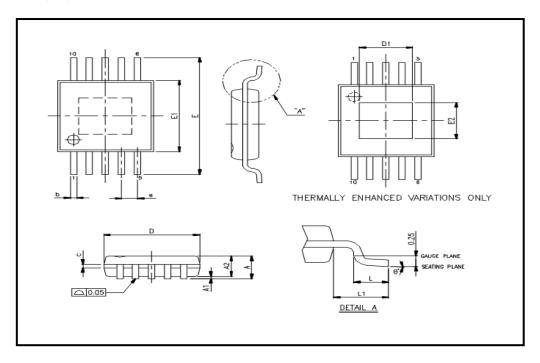


This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.



# **Package Outline**

## MSOP-10L (EP)



Symbols	Min. (mm)	Max. (mm)	
А		1.10	
A1	0	0.15	
A2	0.75	0.95	
b	0.17	0.27	
С	0.05	0.23	
D	3.00 BSC.		
E	4.90 BSC.		
E1	3.00	BSC.	
е	0.50 BSC.		
L	0.4	0.8	
L1	0.95 REF.		
θ°	0	8	

Thermally Enhanced Dimensions					
PAD SIZE	E2 (mm)	D1 (mm)			
75×70E	1.715 REF.	1.600 REF.			

This datasheet contains new product information. Feeling Technology reserves the rights to modify the product specification without notice. No liability is assumed as a result of the use of this product. No rights under any patent accompany the sales of the product.

Website: http://www.feeling-tech.com.tw



#### Note:

- 1. JEDEC Outline: MO187 BA / MO-187 BA-T (Thermally Enhanced Variations Only).
- 2. Dimensions "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or Gate burrs shall not exceed 0.15mm (.0.06in) per side.
- 3. Dimension "E1" does not include inter-lead flash, or protrusion. Inter-lead flash or protrusions shall not exceed 0.25mm (.0.10in) per side.
- 4. Dimension"D22" does not include DAMBAR protrusion. Allowable DAMBAR protrusion shall be 0.08mm total in excess of the "0.22" dimension at maximum material condition. DAMBAR cannot be located on the lower radius of the foot. Minimum space between protrusions